

型号	电阻成分	薄层电阻	温度系数	对应基板	对应电极	推荐烧成条件
Type	Resistance component	Sheet resistanc	TCR (ppm/°C)	Substrate	Electrode	Recommend ed firing conditions
CN01DH	CuNi	10mΩ/□ /20μm	+500	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
CN03DH	CuNi	30mΩ/□ /20μm	-100	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
CNR10H	CuNi	100mΩ/□ /20μm	<±100	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
CNR50H	CuNi	500mΩ/□ /20μm	<±100	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
CN1R5H	CuNi	1.5Ω/□ /20μm	<±100	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
CN3R0H	CuNi	3Ω/□/20 μm	<±100	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
CN6R0H	CuNi	6Ω/□/20 μm	<±100	Al ₂ O ₃	Cu	900 °C 10min
						In N ₂
LB3s	LaB ₆	3Ω/□/20μ m	<±350	Al ₂ O ₃	Cu	850 °C 10min
						In N ₂
LB10s	LaB ₆	10Ω/□/20 μm	<±200	Al ₂ O ₃	Cu	850 °C 10min
						In N ₂
LB100s	LaB ₆	100Ω/□ /20μm	<±50	Al ₂ O ₃	Cu	850 °C 10min
						In N ₂
LB1ks	LaB ₆	1kΩ/□/20 μm	<±50	Al ₂ O ₃	Cu	850 °C 10min
						In N ₂
LB20sNE	LaB ₆	20Ω/□/20 μm	<±250	AlN	Ag	820 °C 10min
						In Air
LB100sNE	LaB ₆	100Ω/□ /20μm	<±100	AlN	Ag	820 °C 10min
						In Air
LB1ksNE	LaB ₆	1kΩ/□/20 μm	<±50	AlN	Ag	820 °C 10min
						In Air

型号	用途/特性	推荐烧成条件	对应基板	涂布方法
Type	Application and Characteristics	Recommend ed firing conditions	Substrate	Coating method
OCG02	外涂层玻璃浆适	Al ₂ O ₃	650 °C 10min	丝网印刷
	无铅、良好的耐电镀性			
	Overcoat glass paste, Lead-free		In N ₂	Screen printing
	Excellent resistance to acid, gray			
OCG10	外涂层玻璃浆适	Al ₂ O ₃	850~900 °C 10min	丝网印刷
	无铅、良好的耐电镀性、透明			
	Overcoat glass paste, Lead-free		In N ₂	Screen printing
	Excellent resistance to acid, Clear			